

# Ahmad Shahedi Shakil

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## Education

### **Bangladesh University of Engineering and Technology (BUET)**

M.Sc. Mechanical Engineering

CGPA: **3.916** out of 4.00 (up to 3<sup>rd</sup> semester)

*Dhaka, Bangladesh*

*October, 2014-Continue*

### **Bangladesh University of Engineering and Technology (BUET)**

B.Sc. Mechanical Engineering (with Honours)

CGPA: **3.84** out of 4.00

Ranking: 4<sup>th</sup> of 134 students graduated in same year.

*Dhaka, Bangladesh*

*July 2014*

### **Dhaka College**

Higher Secondary School Certificate

GPA: **5.00** out of 5.00

*Dhaka, Bangladesh*

*September 2008*

## Work Experiences

### **Bangladesh University of Engineering and Technology (BUET)**

Lecturer, Department of Mechanical Engineering

- Theory courses taught: Engineering Mechanics, Mechanics of Solids and Machine Design.
- Lab courses taught: Mechanical Engineering Drawing Lab, Thermodynamics Lab, Mechanics of Solids Lab, Machine Design Lab, Mechanics of Machinery Lab and Fluid Mechanics Lab.

*Dhaka, Bangladesh*

*August 2014-Present*

### **British American Tobacco, Bangladesh**

Industrial Trainee

- Tasks performed: Learning different operations of cigarette production, quality control analysis of filter rod of cigarette.

*Dhaka, Bangladesh*

*October 2013-November 2013*

## Research and Project Experiences

### **M.Sc thesis**

Predictions of thermal cycling life of PBGA microprocessor components with variation of mechanical properties of the packaging materials.

- Using finite element method to determine damage accumulation of different components of a PBGA package.

### **B.Sc thesis**

1. Design optimization of spur gear based on AGMA approach.

- Developed a MATLAB code for the design based on different requirement, e.g. minimum cost.

2. The effects of substrate copper on the solder joint reliability of a microprocessor package due to thermal cycling.

- Performed some experimental analysis to find the relationship between substrate copper and package thermal cycling life.

### **Junior year project**

Automated bridge dividing system for ship entrance.

## **Publications**

Mohammad Motalab, Ahmad Shahedi Shakil, Toufiq Rahman, Jeffrey C. Suhling; "*Variation of Thermal Cycling Life Prediction of PBGA Microprocessor Components with Substrate Properties*", Journal of Emerging Trends in Engineering and Applied Sciences (JETEAS), 6(5): 371- 376, 2015.

## **Technical Skills**

ANSYS Mechanical • MATLAB • C/C++ • AutoCAD • SolidWorks • MS Office • MS Excel

## **Research Interests**

- Materials and Solid Mechanics
- Micro and Nano Technology
- Electronic Packaging
- Biomechanics

## **Honors & Achievements**

- Received Dean's List Award (awarded for CGPA>3.75 in any year) for each year of undergraduate study.
- Received merit scholarship for academic performance in 7 out of the 8 semesters of undergraduate study.
- Received technical scholarship in undergraduate study.

## **Memberships & Activities**

- Member, Organizing Committee of International Conference of Mechanical Engineering (ICME), 2015 in BUET.
- Member, Mechanical Engineering Association, BUET.
- Organized BUET Robotic Car Race, 2016.
- Participated in undergraduate cricket tournament.